

**Operational Amplifiers** 

# **Ground Sense Operational Amplifiers**

BA10358xx, BA10324Axx, BA2904xxx, BA2904Sxxx, BA2904Wxx BA2902xx, BA2902Sxx

### **General Description**

General purpose BA10358 / BA10324A and high reliability BA2904 / BA2902 integrate two or four independent Op-Amps on a single chip and have some features of high-gain, low power consumption, and wide operating voltage range of 3V to 36V (single power supply).

BA2904W have low input offset voltage(2mV max.).

### Features

- Operable with a single power supply
- Wide operating supply voltage range
- Input and output are operable GND sense
- Low supply current
- High open loop voltage gain
- Wide temperature range

#### Application

- Current sense application
- Buffer application amplifier
- Active filter
- Consumer electronics

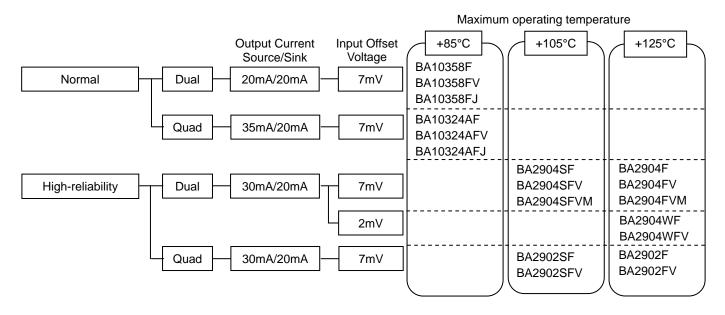
### **Key Specification**

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Wi	de Operating Supply Voltage (sin	gle supply):
	BA10358/BA10324A	+3.0V to +32.0V
	BA2904/BA2902	+3.0V to +36.0V
Wi	de Temperature Range:	
	BA10358/ BA10324A	-40°C~+85°C
	BA2904S/ BA2902S	-40°C~+105°C
	BA2904/ BA2902	-40°C~+125°C
	BA2904W	-40°C~+125°C
🔳 Inp	out Offset Voltage:	
	BA10358/ BA10324A	7mV (Max)
	BA2904S/ BA2902S	7mV (Max)
	BA2904/ BA2902	7mV (Max)
	BA2904W	2mV (Max)
■ Lo	w Input Bias Current:	
	BA10358	45nA (Typ)
	BA10324A	20nA (Typ)
	BA2904S/ BA2902S	20nA (Typ)
	BA2904/ BA2902	20nA (Typ)
	BA2904W	20nA (Typ)

#### Packages

SOP8 SOP-J8 SSOP-B8 MSOP8 SOP14 SOP-J14 SSOP-B14 W(Typ) x D(Typ) x H(Max) 5.00mm x 6.20mm x 1.71mm 4.90mm x 6.00mm x 1.65mm 3.00mm x 6.40mm x 1.35mm 2.90mm x 4.00mm x 0.90mm 8.70mm x 6.20mm x 1.71mm 8.65mm x 6.00mm x 1.65mm 5.00mm x 6.40mm x 1.35mm

## **Selection Guide**



OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

# **Simplified schematic**

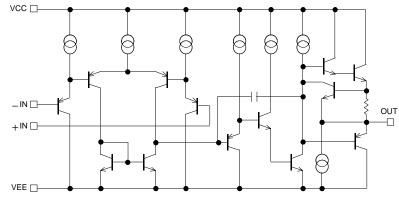
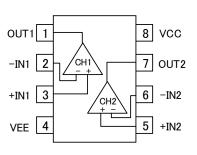


Figure 1. Simplified schematic (one channel only)

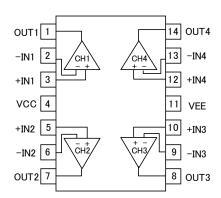
### **Pin Configuration**

BA10358F,BA2904SF,BA2904F,BA2904WF :SOP8 BA10358FV,BA2904SFV,BA2904FV,BA2904WFV :SSOP-B8 BA2904SFVM,BA2904FVM :MSOP8 BA10358FJ :SOP-J8



Pin No.	Pin Name				
1	OUT1				
2	-IN1				
3	+IN1				
4	VEE				
5	+IN2				
6	-IN2				
7	OUT2				
8	VCC				

#### BA10324AF,BA2902SF,BA2902F :SOP14 BA10324AFV,BA2902SFV,BA2902FV :SSOP-B14 BA10324AFJ :SOP-J14



Pin No.	Pin Name			
1	OUT1			
2	-IN1			
3	+IN1			
4	VCC			
5	+IN2			
6	-IN2			
7	OUT2			
8	OUT3			
9	-IN3			
10	+IN3			
11	VEE			
12	+IN4			
13	-IN4			
14	OUT4			

			Package			
SOP8	SSOP-B8	MSOP8	SOP-J8	SOP14	SSOP-B14	SOP-J14
BA10358F BA2904SF BA2904F BA2904WF	BA10358FV BA2904SFV BA2904FV BA2904FV	BA2904SFVM BA2904FVM	BA10358FJ	BA10324AF BA2902SF BA2902F	BA10324AFV BA2902SFV BA2902FV	BA10324AFJ

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# **Ordering Information**

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Part Number.	Package	Packaging and forming specification
BA10358xx	F : SOP8	E2: Embossed tape and reel
BA10324Axx	SOP14	(SOP8/SOP14/SSOP-B8/
BA2904xxx	FV : SSOP-B8	SSOP-B14/SOP-J8/SOP-J14)
BA2904Sxxx	SSOP-B14	TR: Embossed tape and reel
BA2904Wxx	FVM : MSOP8	(MSOP8)
BA2902xx	FJ : SOP-J8	
BA2902Sxx	SOP-J14	

### Lin<u>e-up</u>

Topr	Input Offset Voltage (Max)	Supply Current (Typ)	Pa	ackage	Orderable Part Number
			SOP8	Reel of 2500	BA10358F-E2
		0.5mA	SOP-J8	Reel of 2500	BA10358FJ-E2
40%C to 105%C			SSOP-B8	Reel of 2500	BA10358FV-E2
-40°C to +85°C			SOP14	Reel of 2500	BA10324AF-E2
		0.6mA	SOP-J14	Reel of 2500	BA10324AFJ-E2
			SSOP-B14	Reel of 2500	BA10324AFV-E2
	7mV		SOP8	Reel of 2500	BA2904SF-E2
		0.5mA 0.7mA	SSOP-B8	Reel of 2500	BA2904SFV-E2
-40°C to +105°C			MSOP8	Reel of 3000	BA2904SFVM-TR
			SOP14	Reel of 2500	BA2902SF-E2
			SSOP-B14	Reel of 2500	BA2902SFV-E2
			SOP8	Reel of 2500	BA2904F-E2
		0.5mA	SSOP-B8	Reel of 2500	BA2904FV-E2
			MSOP8	Reel of 3000	BA2904FVM-TR
-40°C to +125°C		0.7	SOP14	Reel of 2500	BA2902F-E2
		0.7mA	SSOP-B14	Reel of 2500	BA2902FV-E2
	2m)/	0.5~	SOP8	Reel of 2500	BA2904WF-E2
	2mV	0.5mA	SSOP-B8	Reel of 2500	BA2904WFV-E2

# Absolute Maximum Ratings (T<sub>A</sub>=25°C)

OBA10358, BA10324A

Parameter	Symbol		Ratings	Unit	
Supply Voltage	V	CC-VEE	+32	V	
		SOP8	620 <sup>(Note 1,7)</sup>		
		SOP-J8	540 <sup>(Note 2,7)</sup>		
	-	SSOP-B8	500 <sup>(Note 3,7)</sup>		
Power dissipation	P <sub>D</sub> SOP14		450 <sup>(Note 4,7)</sup>	mW	
		SOP-J14	820 <sup>(Note 5,7)</sup>		
		SSOP-B14	700 <sup>(Note 6,7)</sup>		
Differential Input Voltage <sup>(Note 8)</sup>		V <sub>ID</sub>	+32	V	
Input Common-mode Voltage Range		V <sub>ICM</sub>	(VEE-0.3) to (VEE+32)	V	
Input Current <sup>(Note 9)</sup>		l <sub>l</sub>	-10	mA	
Wide Operating Supply Voltage		V <sub>opr</sub>	+3.0 to +32.0	V	
Operating Temperature Range		T <sub>opr</sub>	-40 to +85	°C	
Storage Temperature Range		T <sub>stg</sub>	-55 to +125	°C	
Maximum Junction Temperature	T <sub>Jmax</sub>		+125	°C	

Note: Absolute maximum rating item indicates the condition which must not be exceeded. Application if voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

(Note 1) To use at temperature above  $T_A=25^{\circ}C$  reduce 6.2mW.

(Note 2) To use at temperature above  $T_A=25^{\circ}C$  reduce 5.4mW

(Note 3) To use at temperature above  $T_A=25^{\circ}C$  reduce 5.0mW.

(Note 4) To use at temperature above  $T_A=25^{\circ}C$  reduce 4.5mW.

(Note 5) To use at temperature above  $T_A=25^{\circ}C$  reduce 8.2mW

(Note 6) To use at temperature above  $T_A=25^{\circ}C$  reduce 7.0mW.

(Note 7) Mounted on a FR4 glass epoxy PCB 70mm×70mm×1.6mm (Copper foil area less than 3%).

(Note 8) The voltage difference between inverting input and non-inverting input is the differential input voltage.

Then input terminal voltage is set to more than VEE.

(Note 9) An excessive input current will flow when input voltages of less than VEE-0.6V are applied.

The input current can be set to less than the rated current by adding a limiting resistor.

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

# Absolute Maximum Ratings (T<sub>A</sub>=25°C)

OBA2904, BA2902

			Ratings				
Parameter	S	ymbol	BA2904S BA2902S	BA2904, BA2904W BA2902	Unit		
Supply Voltage	VC	C-VEE		36	V		
		SOP8	775 <sup>(No</sup>				
		SSOP-B8		ote 11,15)			
Power dissipation	PD	MSOP8		600 <sup>(Note 12,15)</sup>			
		SOP14	560 <sup>(No</sup>	]			
		SSOP-B14	870 <sup>(Note 14,15)</sup>				
Differential Input Voltage <sup>(Note 16)</sup>		V <sub>ID</sub>	+36				
Input Common-mode Voltage Range		V <sub>ICM</sub>	(VEE-0.3) to (VEE+36)				
Input Current <sup>(Note 17)</sup>		h	-10				
Wide Operating Supply Voltage	V <sub>opr</sub>		+3.0 to +36.0		V		
Operating Temperature Range	T <sub>opr</sub>		-40 to +105	-40 to +125	°C		
Storage Temperature Range	T <sub>stg</sub>		-55 to +150				
Maximum Junction Temperature	T <sub>Jmax</sub>		+150				

(Note 10) To use at temperature above  $T_A=25^{\circ}C$  reduce 6.2mW.

(Note 11) To use at temperature above T<sub>A</sub>=25°C reduce 5.0mW.

(Note 12) To use at temperature above T<sub>A</sub>=25°C reduce 4.8mW.

(Note 13) To use at temperature above  $T_A=25^{\circ}C$  reduce 4.5mW.

(Note 14) To use at temperature above  $T_A=25^{\circ}C$  reduce 7.0mW.

(Note 15) Mounted on a FR4 glass epoxy PCB 70mm×70mm×1.6mm (Copper foil area less than 3%).

(Note 16) The voltage difference between inverting input and non-inverting input is the differential input voltage.

Then input terminal voltage is set to more than VEE.

(Note 17) An excessive input current will flow when input voltages of less than VEE-0.6V are applied.

The input current can be set to less than the rated current by adding a limiting resistor.

**Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

# **Electrical Characteristics**

OBA10358 (Unless otherwise specified VCC=+5V, VEE=0V, T<sub>A</sub>=25°C)

Parameter	Symbol	Limits			Unit	Condition	
Falameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
Input Offset Voltage (Note 18)	V <sub>IO</sub>	-	2	7	mV	OUT=1.4V	
Input Offset Current (Note 18)	I <sub>IO</sub>	-	5	50	nA	OUT=1.4V	
Input Bias Current (Note 19)	Ι <sub>Β</sub>	-	45	250	nA	OUT=1.4V	
Supply Current	Icc	-	0.5	1.2	mA	RL=∞, All Op-Amps	
Maximum Output Voltage(High)	V <sub>OH</sub>	3.5	-	-	V	RL=2kΩ	
Maximum Output Voltage(Low)	Vol	-	-	250	mV	RL=∞, All Op-Amps	
Lorge Signal Valtage Cain	٨	25	100	-	V/mV	RL≧2kΩ, VCC=15V	
Large Signal Voltage Gain	A <sub>V</sub>	88	100	-	dB	OUT=1.4 to 11.4V	
Input Common-mode Voltage Range	VICM	0	-	VCC-1.5	V	(VCC-VEE)=5V OUT=VEE+1.4V	
Common-mode Rejection Ratio	CMRR	65	80	-	dB	OUT=1.4V	
Power Supply Rejection Ratio	PSRR	65	100	-	dB	VCC=5 to 30V	
Output Source Current	ISOURCE	10	20	-	mA	VIN+=1V, VIN-=0V OUT=0V, 1CH is short circuit	
Output Sink Current	I <sub>SINK</sub>	10	20	-	mA	VIN+=0V, VIN-=1V OUT=5V, 1CH is short circuit	
Channel Separation	CS	-	120	-	dB	f=1kHz, input referred	
Slew Rate	SR	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF	
Gain Band Width	GBW	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF	

(Note 18) Absolute value

(Note 19) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

### OBA10324A (Unless otherwise specified VCC=+5V, VEE=0V, T<sub>A</sub>=25°C)

Parameter	Symbol	VEE=0V, T <sub>A</sub> =25°C) Limits			Unit	0	
Parameter	Symbol	Min. Typ. N		Max.	Unit	Condition	
Input Offset Voltage (Note 20)	V <sub>IO</sub>	-	2	7	mV	OUT=1.4V	
Input Offset Current (Note 20)	I <sub>IO</sub>	-	5	50	nA	OUT=1.4V	
Input Bias Current (Note 21)	I <sub>B</sub>	-	20	250	nA	OUT=1.4V	
Supply Current	Icc	-	0.6	2	mA	RL=∞, All Op-Amps	
Maximum Output Voltage(High)	V <sub>OH</sub>	3.5	-	-	V	RL=2kΩ	
Maximum Output Voltage(Low)	V <sub>OL</sub>	-	-	250	mV	RL=∞, All Op-Amps	
Large Signal Voltage Gain	Av	25	100	-	V/mV	RL≧2kΩ, VCC=15V	
Large Signal Voltage Gain	AV	88	100	-	dB	OUT=1.4 to 11.4V	
Input Common-mode Voltage range	V <sub>ICM</sub>	0	-	VCC-1.5	V	(VCC-VEE)=5V OUT=VEE+1.4V	
Common-mode Rejection Ratio	CMRR	65	75	-	dB	OUT=1.4V	
Power Supply Rejection Ratio	PSRR	65	100	-	dB	VCC=5 to 30V	
Output Source Current	I <sub>SOURCE</sub>	20	35	-	mA	VIN+=1V, VIN-=0V OUT=0V, 1CH is short circuit	
Output Sink Current	I <sub>SINK</sub>	10	20	-	mA	VIN+=0V, VIN-=1V OUT=5V, 1CH is short circuit	
Channel Separation	CS	-	120	-	dB	f=1kHz, input referred	
Slew Rate	SR	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF	
Gain Band Width	GBW	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF	

(Note 20) Absolute value

(Note 21) Current direction: Since first input stage is composed with PNP transistor, input bias current flows out of IC.

Parameter	Symbol	Temperature		Limits		Unit	Condition	
Parameter	Symbol	Range	Min.	Тур.	Max.	Unit		
Input Offset Voltage (Note 22,23)	V <sub>IO</sub>	25°C	-	2	7	mV	OUT=1.4V	
input encot voltage	•10	Full range	-	-	10		VCC=5 to 30V, OUT=1.4V	
Input Offset Voltage Drift	ΔV <sub>IO</sub> /ΔΤ		-	±7	-	µV/°C	OUT=1.4V	
Input Offset Current (Note 22,23)	I <sub>IO</sub>	25°C	-	2	50	nA	OUT=1.4V	
	10	Full range	-	-	200			
Input Offset Current Drift	$\Delta I_{IO} / \Delta T$	-	-	±10	-	pA/°C	OUT=1.4V	
Input Bias Current (Note 22,23)	I <sub>B</sub>	25°C	-	20	250	nA	OUT=1.4V	
	.0	Full range	-	-	250			
Supply Current (Note 23)	Icc	25°C	-	0.5	1.2	mA	RL=∞, All Op-Amps	
		Full range	-	-	2			
Maximum Output Voltage(High) (Note 23)	V <sub>OH</sub>	25°C	3.5	-	-	V	RL=2kΩ VCC=30V, RL=10kΩ	
		Full range	27	28	-		VCC=30V, RL=10K22	
Maximum Output Voltage(Low) (Note 23)	V <sub>OL</sub>	Full range	-	5	20	mV	RL=∞, All Op-Amps	
Large Signal Voltage Gain	Av	25°C	25	100	-	V/mV	RL≧2kΩ, VCC=15V	
			88	100	-	dB	OUT=1.4 to 11.4V	
Input Common-mode Voltage Range	V <sub>ICM</sub>	25°C	0	-	VCC-1.5	V	(VCC-VEE)=5V OUT=VEE+1.4V	
Common-mode Rejection Ratio	CMRR	25°C	50	80	-	dB	OUT=1.4V	
Power Supply Rejection Ratio	PSRR	25°C	65	100	-	dB	VCC=5 to 30V	
Output Source Current (Note 23,24)	laguage	25°C	20	30	-	mA	VIN+=1V, VIN-=0V	
Supar Source Current	ISOURCE	Full range	10	-	-		OUT=0V, 1CH is short circuit	
		25°C	10	20	-	mA	VIN+=0V, VIN-=1V	
Output Sink Current (Note 23,24)	I <sub>SINK</sub>	Full range	2	-	-		OUT=5V, 1CH is short circuit	
	Onvit	25°C	12	40	-	μA	VIN+=0V, VIN-=1V OUT=200mV	
Channel Separation	CS	25°C	-	120	-	dB	f=1kHz, input referred	
Slew rate	SR	25°C	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF	
Gain Band Width	GBW	25°C	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF	
Input referred noise voltage	V <sub>N</sub>	25°C	-	40	-	nV/√Hz	VCC=15V, VEE=-15V RS=100Ω, Vi=0V, f=1kHz	

### OBA2904, BA2904S (Unless otherwise specified VCC=+5V, VEE=0V)

(Note 22) Absolute value

(Note 23) BA2904S :Full range -40 to +105°C BA2904 :Full range -40 to +125°C

(Note 24) Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

Parameter	Symbol	Temperature Range	Limits			Unit	O and diffient
	Symbol		Min.	Тур.	Max.	Unit	Condition
Input Offset Voltage (Note 25)	V <sub>IO</sub>	25°C	-	0.5	2	mV	OUT=1.4V
Input Offset Voltage Drift	$\Delta V_{IO} / \Delta T$	-	-	±7	-	µV/°C	OUT=1.4V
Input Offset Current (Note 25)	I <sub>IO</sub>	25°C	-	2	50	nA	OUT=1.4V
Input Offset Current Drift	$\Delta I_{IO} / \Delta T$	-	-	±10	-	pA/°C	OUT=1.4V
Input Bias Current (Note 25)	IB	25°C	-	20	250	nA	OUT=1.4V
	IB	Full range	-	-	250		
Supply Current	l	25°C	-	0.5	1.2	mA	RL=∞, All Op-Amps
	I <sub>CC</sub>	Full range	-	-	1.2		RL=∞, All Op-Amps
Maximum Output Voltage(High)	V	25°C	3.5	-	-	V	RL=2kΩ
	V <sub>OH</sub>	Full range	27	28	-		VCC=30V, RL=10kΩ
Maximum Output Voltage(Low)	V <sub>OL</sub>	Full range	-	5	20	mV	RL=∞, All Op-Amps
Large Signal Voltage Gain	•	25°C	25	100	-	V/mV dB	RL≧2kΩ, VCC=15V OUT=1.4 to 11.4V
	A <sub>V</sub>		88	100	-		
Input Common-mode Voltage Range	VICM	25°C	0	-	VCC-1.5	V	(VCC-VEE)=5V OUT=VEE+1.4V
Common-mode Rejection Ratio	CMRR	25°C	50	80	-	dB	OUT=1.4V
Power Supply Rejection Ratio	PSRR	25°C	65	100	-	dB	VCC=5 to 30V
Output Source Current (Note 26)	1	25°C	20	30	-	mA	VIN+=1V, VIN-=0V
	ISOURCE	Full range	10	-	-		OUT=0V, 1CH is short circuit
Output Sink Current (Note 26)		25°C	10	20	-	mA	VIN+=0V, VIN-=1V OUT=5V, 1CH is short circuit
	I <sub>SINK</sub>	Full range	2	-	-		
	·Silvix	25°C	12	40	-	μA	VIN+=0V, VIN-=1V OUT=200mV
Channel Separation	CS	25°C	-	120	-	dB	f=1kHz, input referred
Slew rate	SR	25°C	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF
Gain Band Width	GBW	25°C	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100pF
Input referred noise voltage	V <sub>N</sub>	25°C	-	40	-	nV/√Hz	VCC=15V, VEE=-15V RS=100Ω, Vi=0V, f=1kHz

#### OBA2904W (Unless otherwise specified VCC=+5V, VEE=0V)

(Note 25) Absolute value

(Note 26) Under high temperatures, please consider the power dissipation when selecting the output current.
 When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

BA2902, BA2902S (Unless otherwise s	Symbol	Temperature Range	, <u>, , , ,</u>				
Parameter			Min.	Тур.	Max.	Unit	Condition
Input Offset Voltage (Note 27,28)	V <sub>IO</sub>	25°C	-	2	7	mV	OUT=1.4V
		Full range	-	-	10		VCC=5 to 30V, OUT=1.4V
Input Offset Voltage Drift	$\Delta V_{IO} / \Delta T$	-	-	±7	-	µV/°C	OUT=1.4V
Input Offset Current (Note 27,28)	I <sub>IO</sub>	25°C	-	2	50	nA	OUT=1.4V
		Full range	-	-	200		
Input Offset Current Drift	$\Delta I_{IO} / \Delta T$	-	-	±10	-	pA/°C	OUT=1.4V
Input Bias Current (Note 27,28)	Ι <sub>Β</sub>	25°C	-	20	250	nA	OUT=1.4V
		Full range	-	-	250		
Supply Current (Note 28)	I <sub>CC</sub>	25°C	-	0.7	2	mA	RL=∞, All Op-Amps
		Full range	-	-	3		
Maximum Output Voltage(High) (Note 28)	V <sub>OH</sub>	25°C	3.5	-	-	V	RL=2kΩ
	• 011	Full range	27	28	-		VCC=30V, RL=10kΩ
Maximum Output Voltage(Low) (Note 28)	V <sub>OL</sub>	Full range	-	5	20	mV	RL=∞, All Op-Amps
Large Signal Voltage Gain	Av	25°C	25	100	-	V/mV	RL≧2kΩ, VCC=15V
			88	100	-	dB	OUT=1.4 to 11.4V
Input Common-mode Voltage Range	VICM	25°C	0	-	VCC-1.5	V	(VCC-VEE)=5V OUT=VEE+1.4V
Common-mode Rejection Ratio	CMRR	25°C	50	80	-	dB	OUT=1.4V
Power Supply Rejection Ratio	PSRR	25°C	65	100	-	dB	VCC=5 to 30V
Output Source Current (Note 28,29)	I <sub>SOURCE</sub>	25°C	20	30	-	mA	VIN+=1V, VIN-=0V OUT=0V 1CH is short circuit
		Full range	10	-	-		
Output Sink Current (Note 28,29)	I <sub>SINK</sub>	25°C	10	20	-	mA	VIN+=0V, VIN-=1V
		Full range	2	-	-	117.	OUT=5V, 1CH is short circuit
		25°C	12	40	-	μA	VIN+=0V, VIN-=1V OUT=200mV
Channel Separation	CS	25°C	-	120	-	dB	f=1kHz, input referred
Slew rate	SR	25°C	-	0.2	-	V/µs	VCC=15V, Av=0dB RL=2kΩ, CL=100pF
Gain Band Width	GBW	25°C	-	0.5	-	MHz	VCC=30V, RL=2kΩ CL=100p
Input referred noise voltage	V <sub>N</sub>	25°C	-	40	-	nV/√Hz	VCC=15V, VEE=-15V RS=100Ω, Vi=0V, f=1kHz

### OBA2902, BA2902S (Unless otherwise specified VCC=+5V, VEE=0V)

(Note 27) Absolute value

(Note 28) BA2902S :Full range -40 to +105°C ,BA2902 :Full range -40 to +125°C

(Note 29) Under high temperatures, please consider the power dissipation when selecting the output current.

When the output terminal is continuously shorted the output current reduces the internal temperature by flushing.

### **Description of Electrical Characteristics**

Described below are descriptions of the relevant electrical terms used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacturer's document or general document.

#### 1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

- Supply Voltage (VCC/VEE)
   Indicates the maximum voltage that can be applied between the positive power supply terminal and negative power supply terminal without deterioration or destruction of characteristics of internal circuit.
- (2) Differential Input Voltage (V<sub>ID</sub>) Indicates the maximum voltage that can be applied between non-inverting and inverting terminals without damaging the IC.
- (3) Input Common-mode Voltage Range (V<sub>ICM</sub>) Indicates the maximum voltage that can be applied to the non-inverting and inverting terminals without deterioration or destruction of electrical characteristics. Input common-mode voltage range of the maximum ratings does not assure normal operation of IC. For normal operation, use the IC within the input common-mode voltage range characteristics.
- (4) Power dissipation (P<sub>D</sub>)

Indicates the power that can be consumed by the IC when mounted on a specific board at the ambient temperature 25°C (normal temperature). As for package product, Pd is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package.

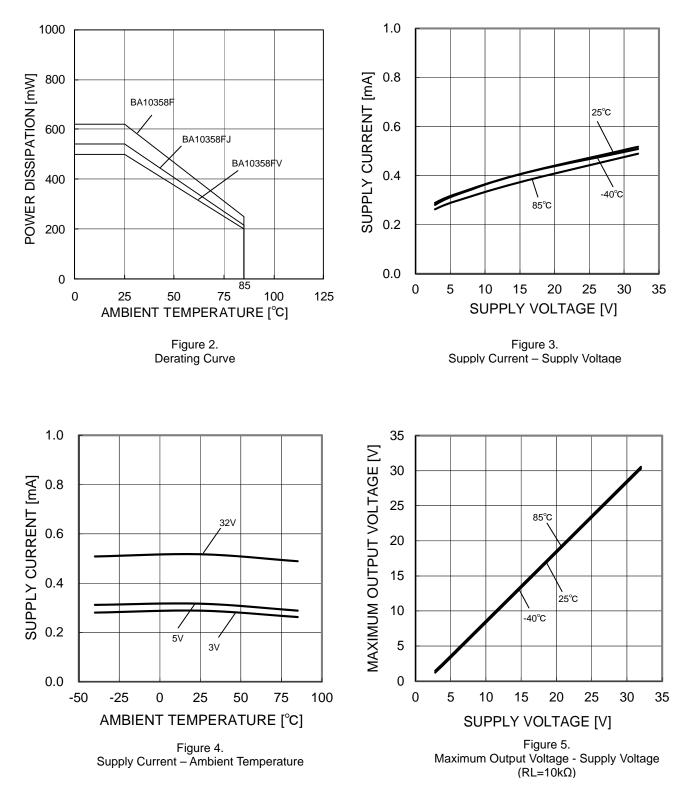
### 2. Electrical characteristics

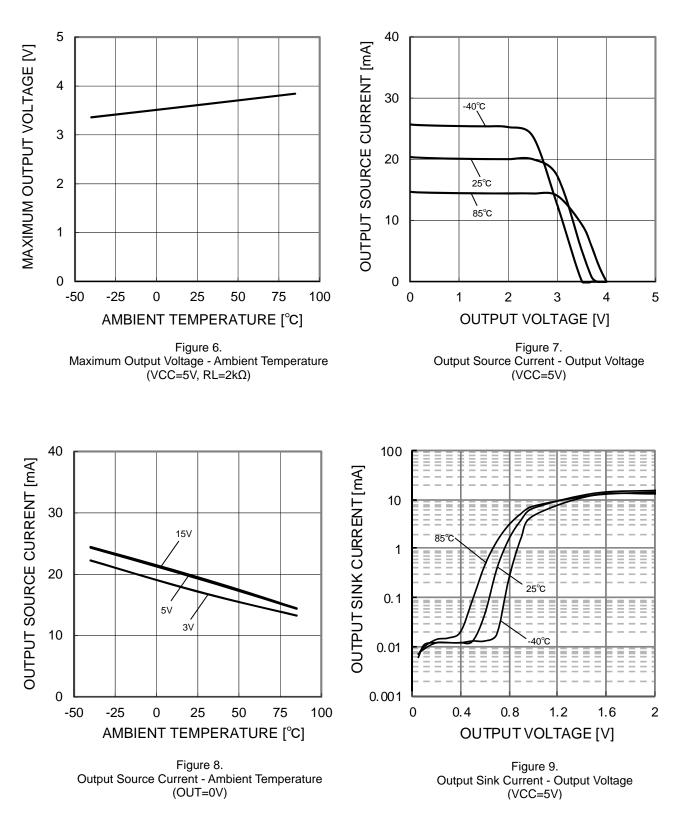
- Input Offset Voltage (V<sub>IO</sub>)
   Indicates the voltage difference between non-inverting terminal and inverting terminals. It can be translated into the input voltage difference required for setting the output voltage at 0 V.
- (2) Input Offset Voltage drift ( $\Delta V_{IO} / \Delta T$ ) Denotes the ratio of the input offset voltage fluctuation to the ambient temperature fluctuation.
- Input Offset Current (I<sub>IO</sub>)
   Indicates the difference of input bias current between the non-inverting and inverting terminals.
- (4) Input Offset Current Drift (△lio/△T)
   Signifies the ratio of the input offset current fluctuation to the ambient temperature fluctuation.
- (4) Input Bias Current (I<sub>B</sub>) Indicates the current that flows into or out of the input terminal. It is defined by the average of input bias currents at the non-inverting and inverting terminals.
- (5) Supply Current (ICC) Indicates the current that flows within the IC under specified no-load conditions.
- (7) Maximum Output Voltage(High) / Maximum Output Voltage(Low) (VOH/VOL) Indicates the voltage range of the output under specified load condition. It is typically divided into maximum output voltage High and low. Maximum output voltage high indicates the upper limit of output voltage. Maximum output voltage low indicates the lower limit.
- (8) Large Signal Voltage Gain (Av)
   Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting terminal and inverting terminal. It is normally the amplifying rate (gain) with reference to DC voltage.
   Av = (Output voltage) / (Differential Input voltage)
- (9) Input Common-mode Voltage Range (V<sub>ICM</sub>)
   Indicates the input voltage range where IC normally operates.
- (10) Common-mode Rejection Ratio (CMRR) Indicates the ratio of fluctuation of input offset voltage when the input common mode voltage is changed. It is normally the fluctuation of DC. CMRR = (Change of Input common-mode voltage)/(Input offset fluctuation)

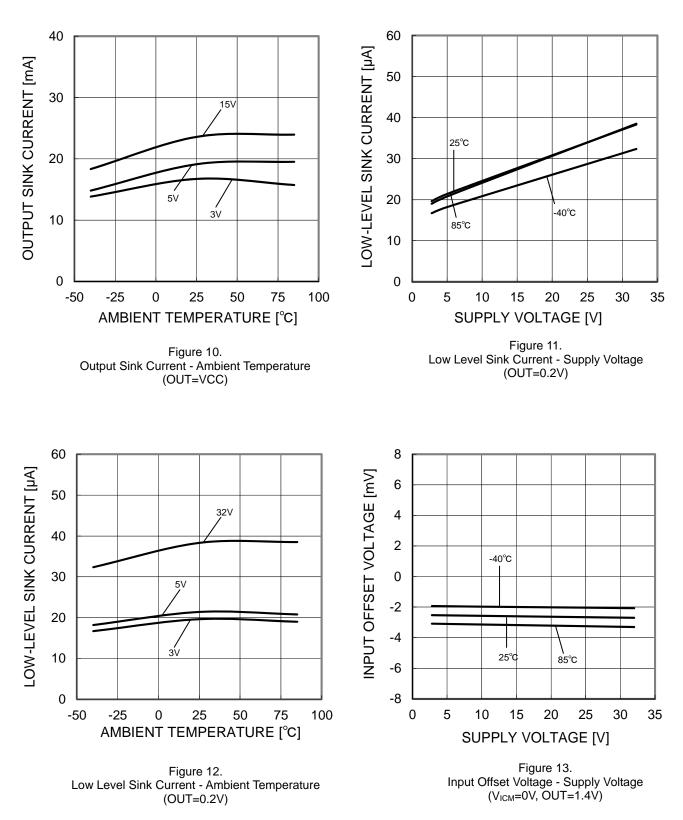
- Power Supply Rejection Ratio (PSRR)
   Indicates the ratio of fluctuation of input offset voltage when supply voltage is changed.
   It is normally the fluctuation of DC.
   PSRR= (Change of power supply voltage)/(Input offset fluctuation)
- (12) Output Source Current/ Output Sink Current (I<sub>source</sub> / I<sub>sink</sub>) The maximum current that can be output from the IC under specific output conditions. The output source current indicates the current flowing out from the IC, and the output sink current indicates the current flowing into the IC. indicates the current flowing out from the IC, and the output sink current indicates the current flowing into the IC.
- (13) Channel Separation (CS) Indicates the fluctuation in the output voltage of the driven channel with reference to the change of output voltage of the channel which is not driven.
- (14) Slew Rate (SR)Indicates the ratio of the change in output voltage with time when a step input signal is applied.
- (15) Gain Bandwidth (GBW) The product of the open-loop voltage gain and the frequency at which the voltage gain decreases 6dB/octave.
- (16) Input Referred Noise Voltage (V<sub>N</sub>) Indicates a noise voltage generated inside the operational amplifier equivalent by ideal voltage source connected in series with input terminal.

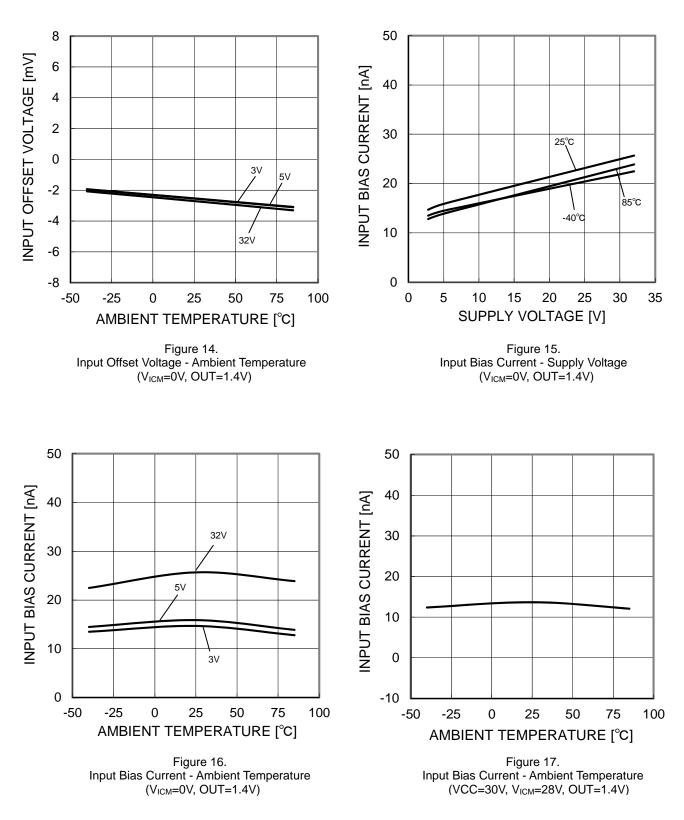
### **Typical Performance Curves**

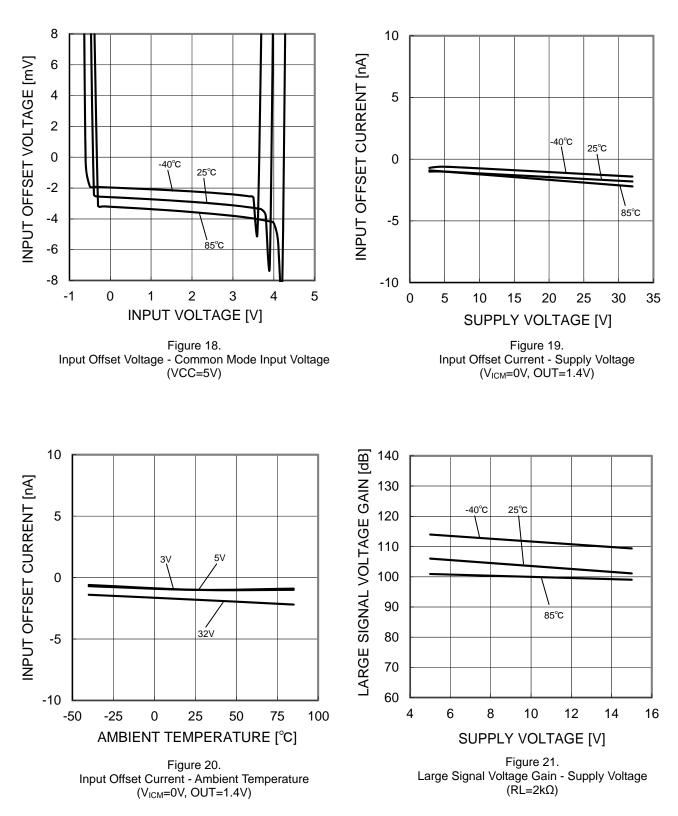
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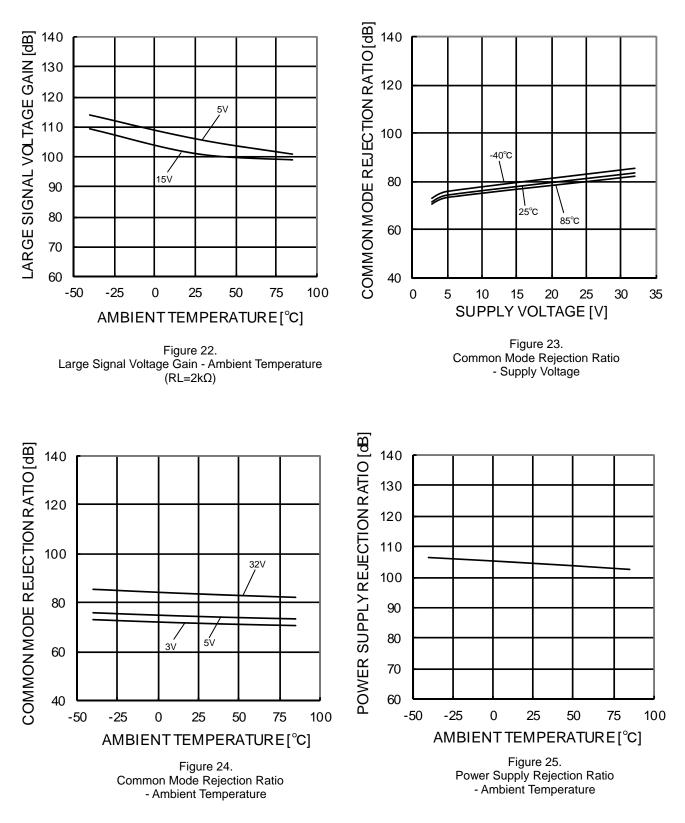


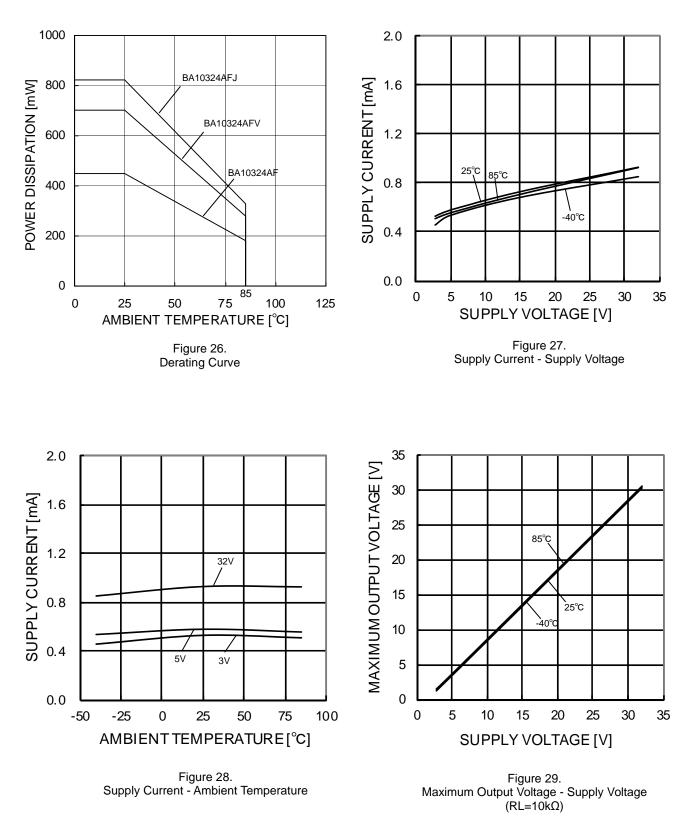


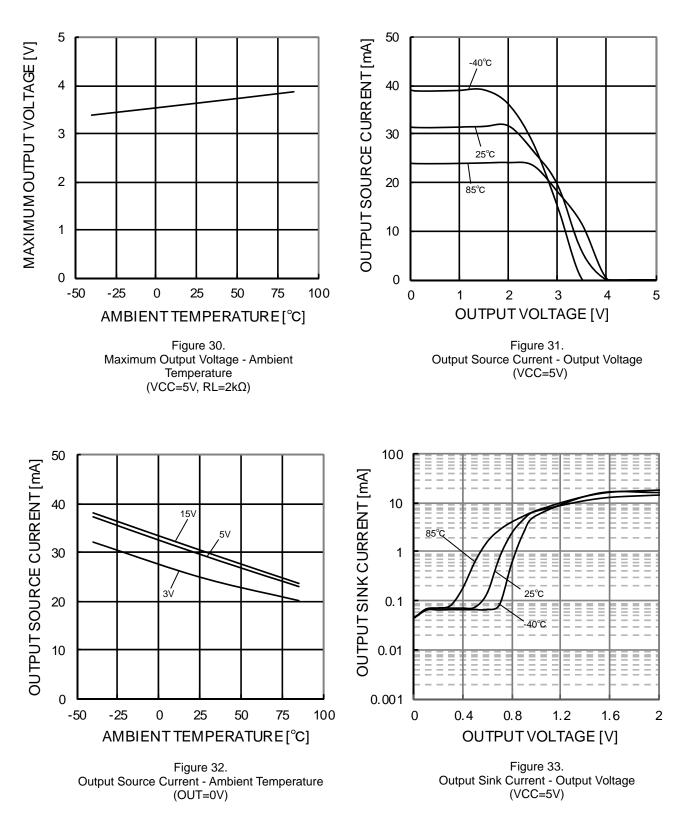


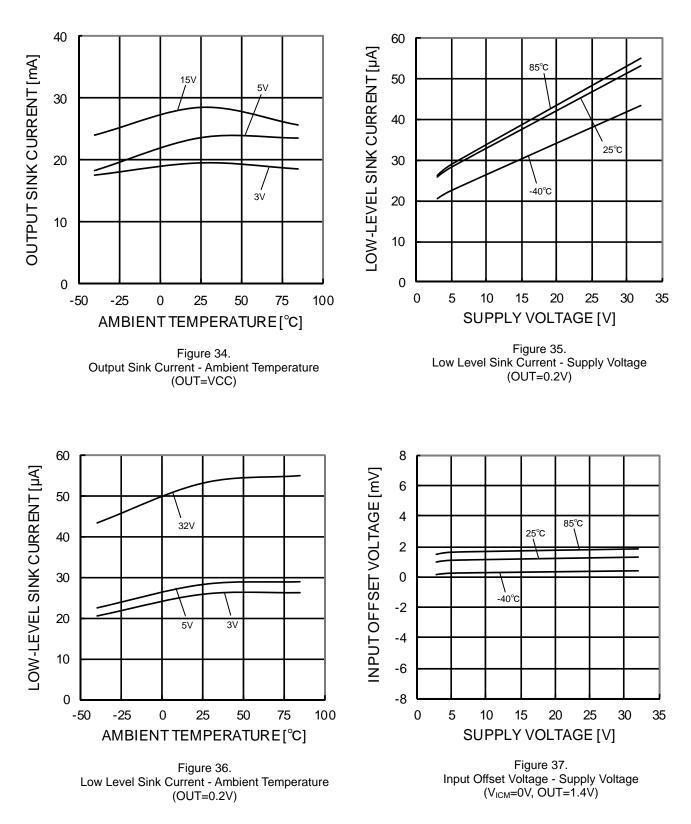


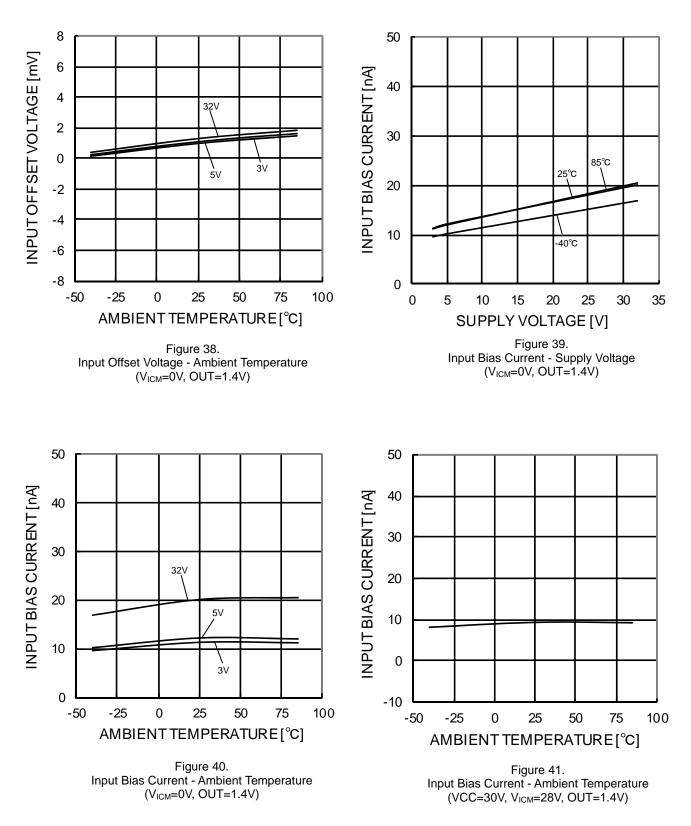


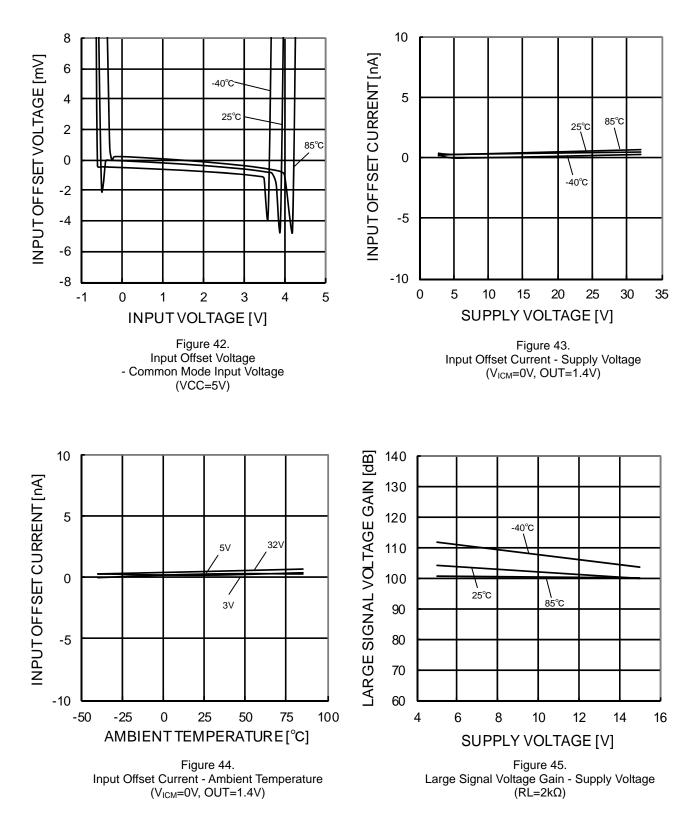




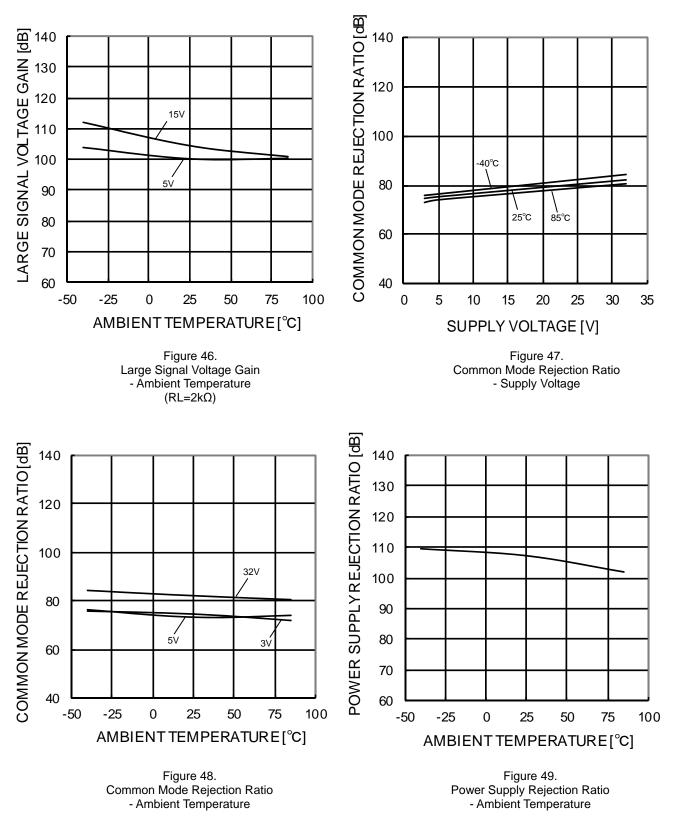


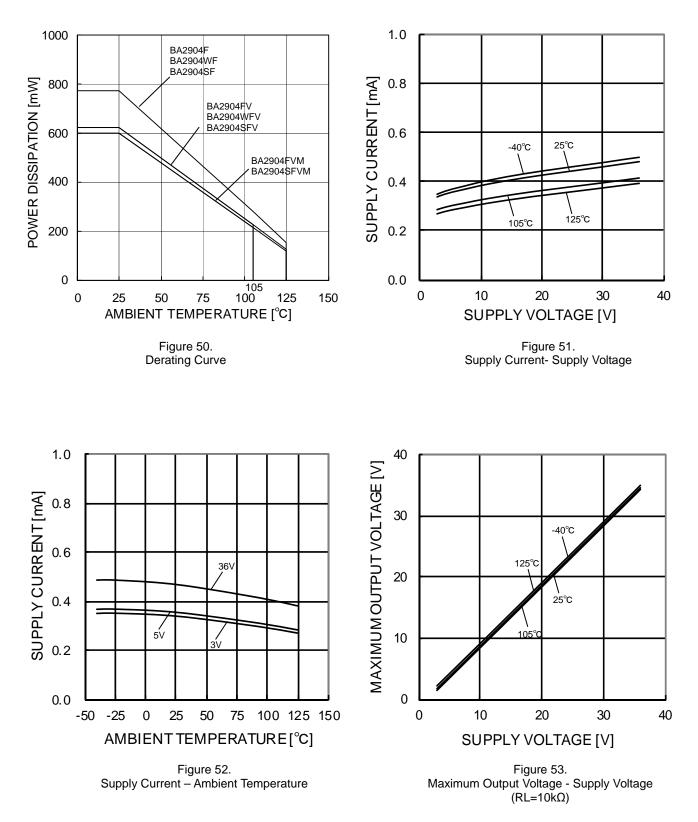




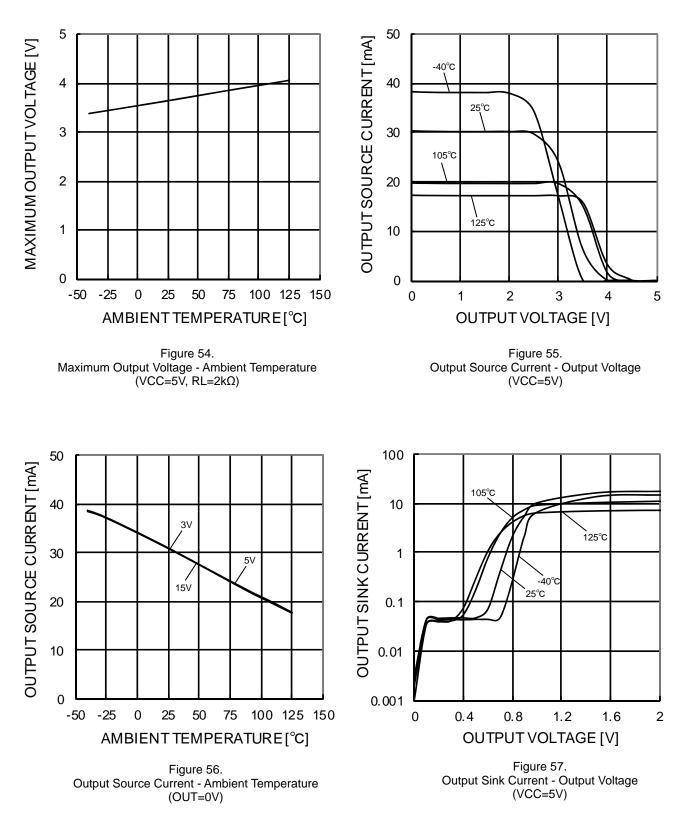


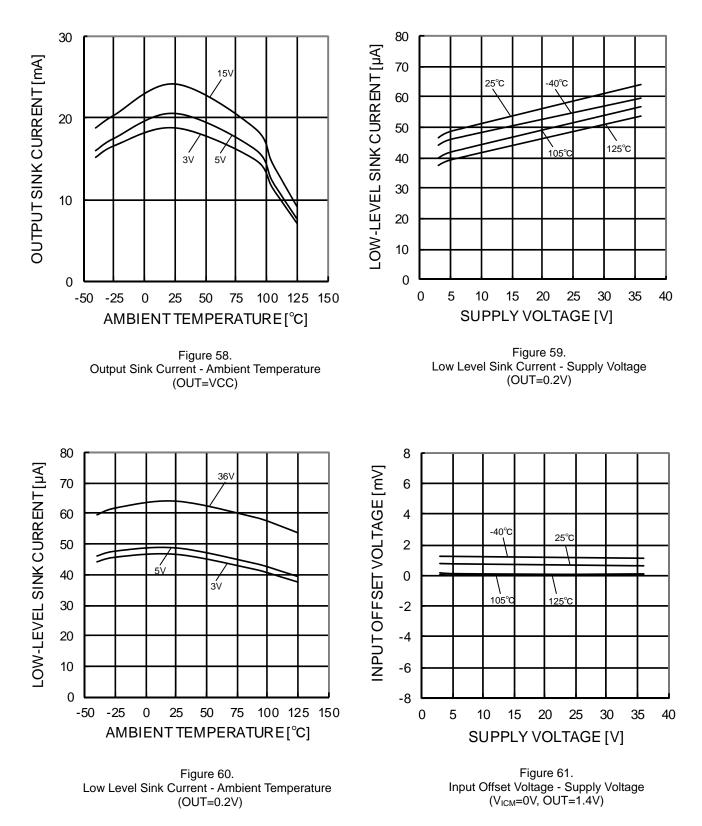


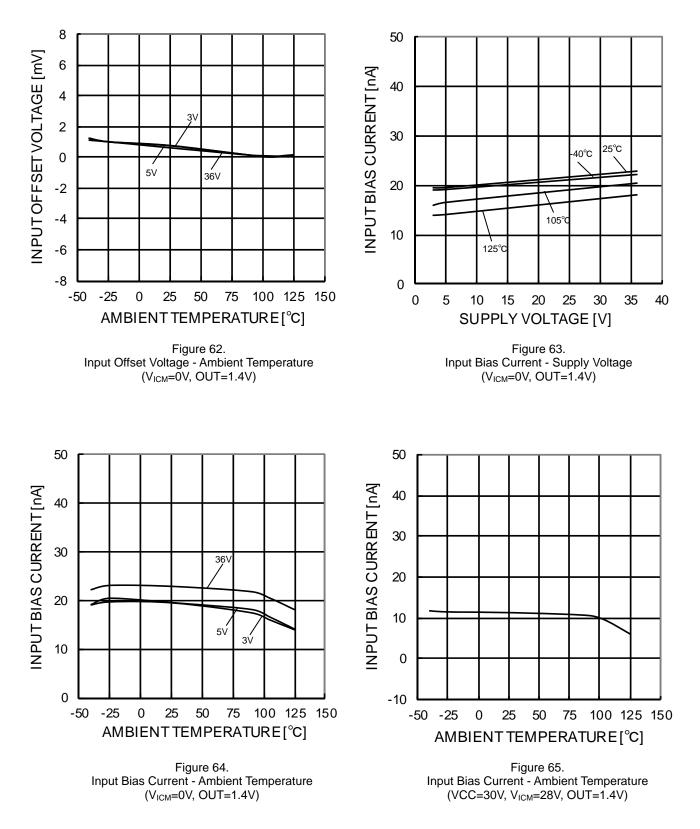


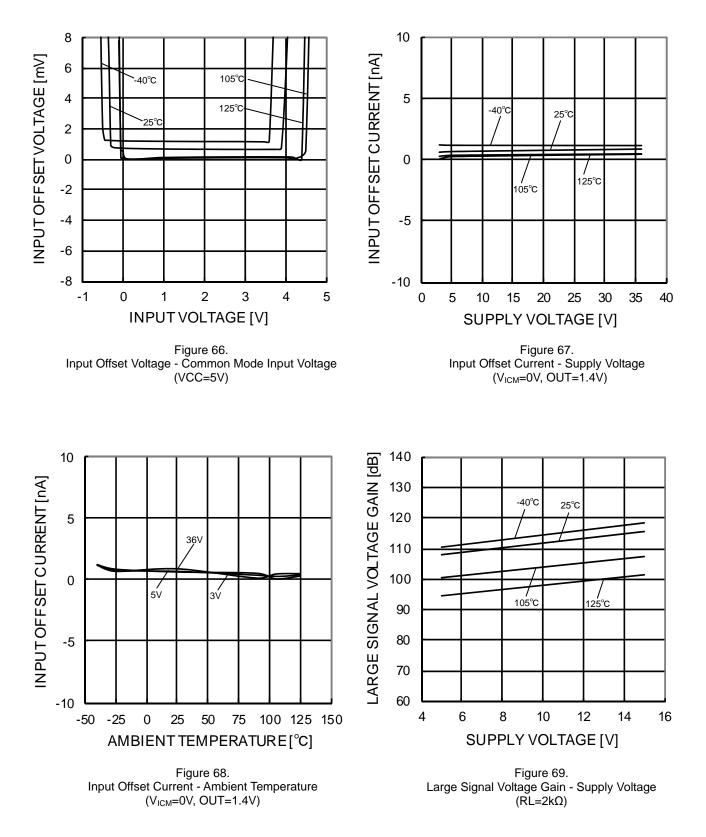


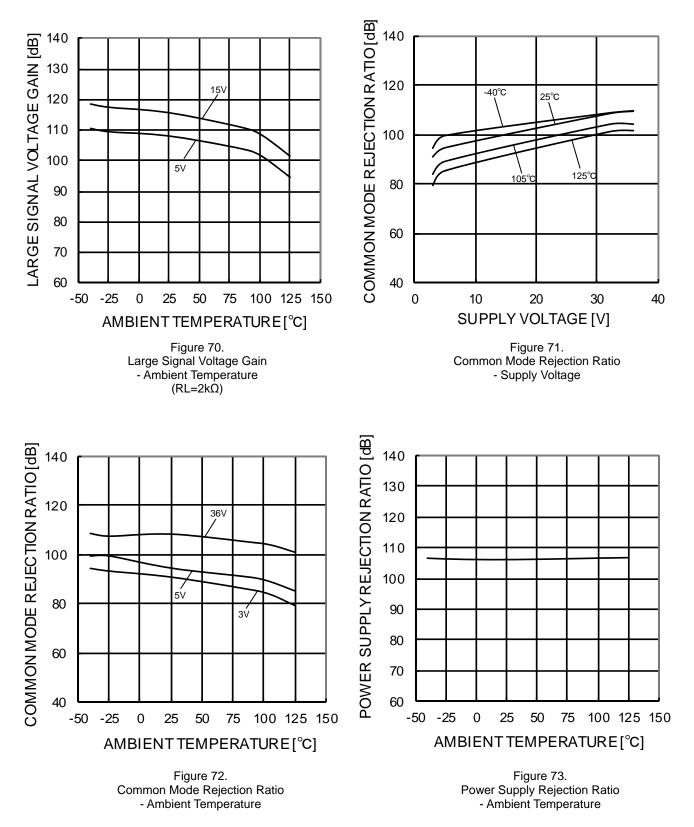
(\*) The above data is measurement value of typical sample, it is not guaranteed. BA2904, BA2904W : -40°C to  $+125^{\circ}$ C BA2904S : -40°C to  $+105^{\circ}$ C

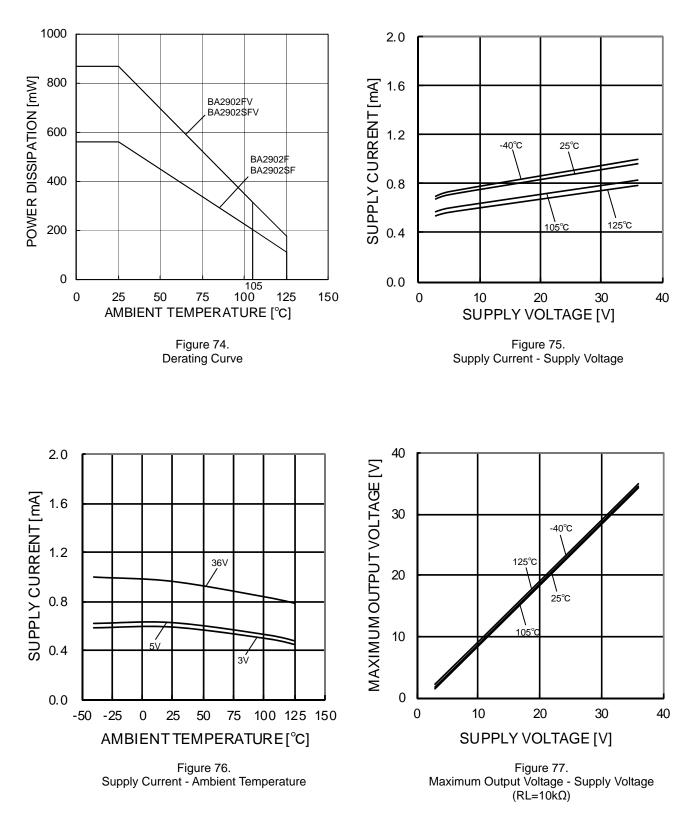




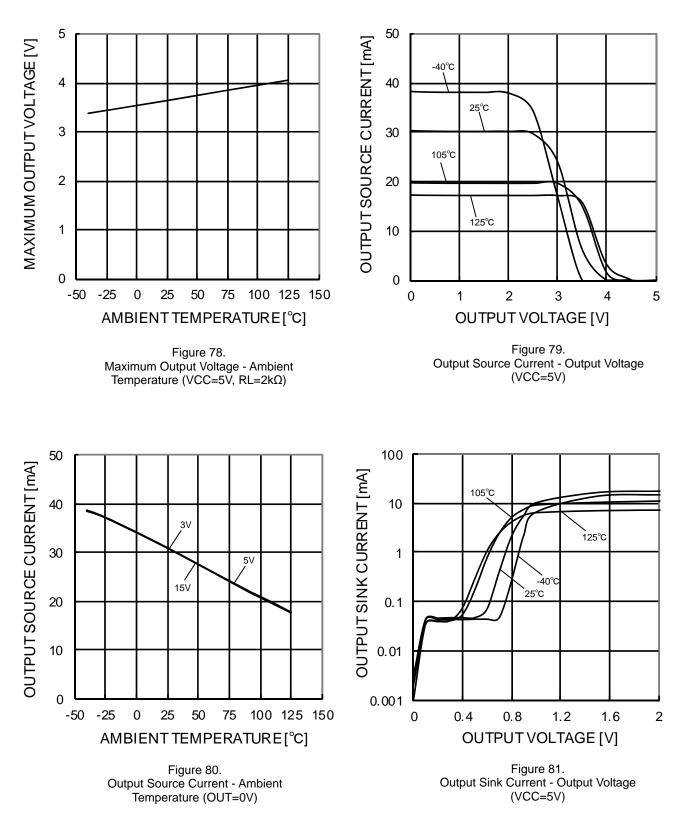


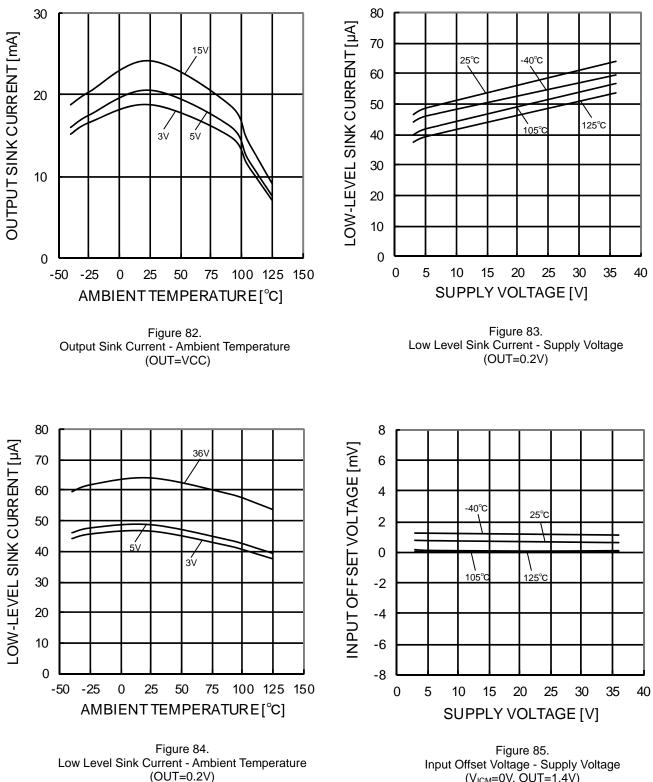




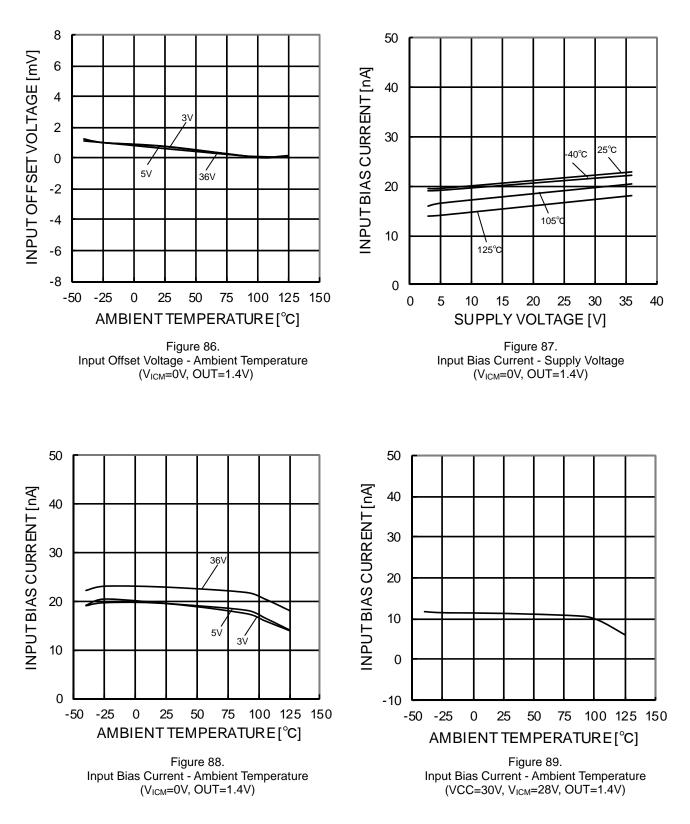


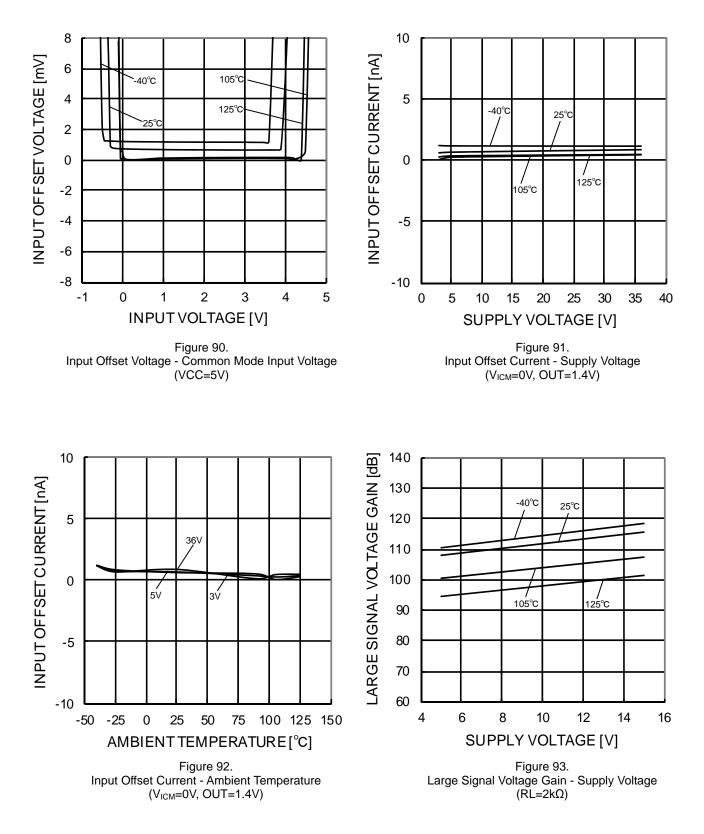
(\*) The above data is measurement value of typical sample, it is not guaranteed. BA2902 : -40°C to +125°C BA2902S : -40°C to +105°C

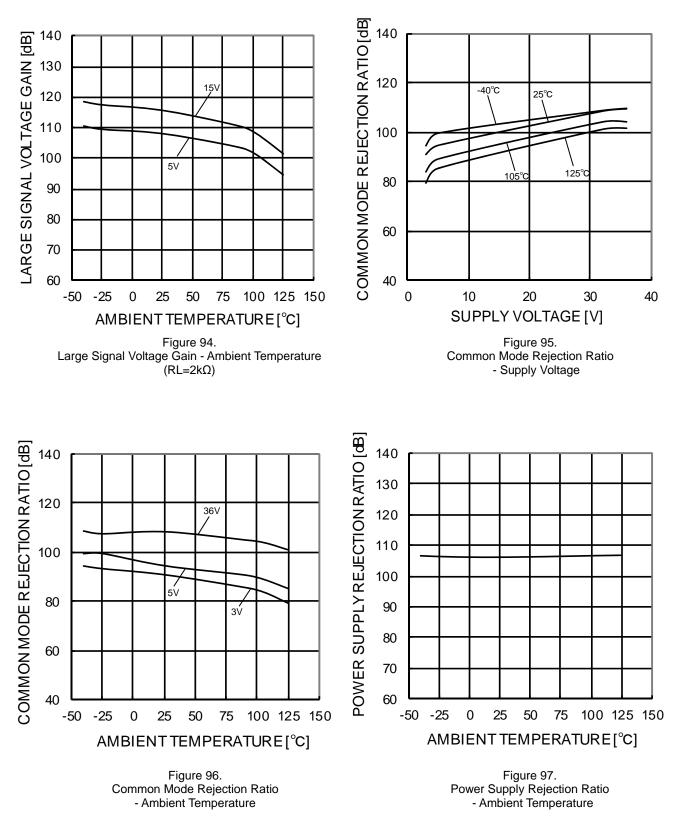




 $(V_{ICM}=0V, OUT=1.4V)$ 







# **Application Information** NULL method condition for Test Circuit 1

	531 011	cuit i								VC	C, VEE	Ξ, Εκ, Vιc	M Unit : V
Parameter	VF	S1	S1 S2 S				0358 )324A		BA2904 BA2902			calculation	
					VCC	VEE	Eκ	VICM	VCC	VEE	Eκ	VICM	
Input Offset Voltage	$V_{F1}$	ON	ON	OFF	5	0	-1.4	0	5 to 30	0	-1.4	0	1
Input Offset Current	$V_{F2}$	OFF	OFF	OFF	5	0	-1.4	0	5	0	-1.4	0	2
Input Ding Current	$V_{F3}$	OFF	ON	OFF	5	0	-1.4	0	5	0	-1.4	0	3
Input Bias Current	$V_{F4}$	ON	OFF	OFF	Э	0							
	$V_{F5}$	ON C	ON	ON	15	0	-1.4	0	15	0	-1.4	0	- 4
Large Signal Voltage Gain	$V_{F6}$				15	0	-11.4	0	15	0	-11.4	0	
Common-mode Rejection Ratio	$V_{F7}$				5	0	-1.4	0	5	0	-1.4	0	
(Input common-mode Voltage Range)	V <sub>F8</sub>	ON	ON	ON OFF	5	0	-1.4	3.5	5	0	-1.4	3.5	5
Power Supply	$V_{F9}$				5	0	-1.4	0	5	0	-1.4	0	6
Rejection Ratio	$V_{F10}$	ON	ON	OFF	30	0	-1.4	0	30	0	-1.4	0	6

-Calculation-

1. Input Offset Voltage (Vio)

$$V_{IO} = \frac{|V_{F1}|}{1 + R_F/R_S}$$
 [V]

2. Input Offset Current (lio)

	V <sub>F2</sub> -V <sub>F1</sub>		r ^ 1
I <sub>IO</sub> =	$R_I \times (1+R_F/R_S)$	_	[A]

 $|V_{F2}-V_{F1}|$ 

3. Input Bias Current (Ib)

4. Large Signal Voltage Gain (Av)

5. Common-mode Rejection Ration (CMRR)

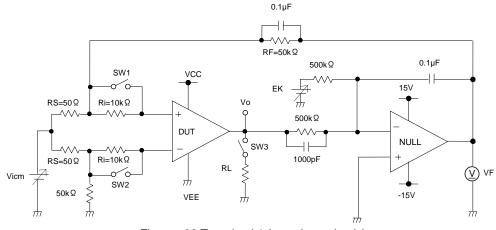
 $|V_{F4}-V_{F3}|$ [A] Ι<sub>Β</sub>  $2 \times R_{I} \times (1 + R_{F}/R_{S})$ 

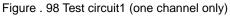
 $A_V = 20 \text{Log} \quad \frac{10 \times (1 + R_F/R_S)}{10 \times 10^{-10}} \text{ [dB]}$ |V<sub>F5</sub>-V<sub>F6</sub>|

CMRR=20Log 
$$\frac{3.5 \times (1+R_F/R_S)}{|V_{F8}-V_{F7}|}$$
 [dB]

6. Power supply rejection ratio (PSRR)

$$PSRR = 20Log \quad \frac{25 \times (1 + R_F/R_S)}{|V_{F10} - V_{F9}|} \text{ [dB]}$$





# Switch Condition for Test Circuit 2

SW No.	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12	SW 13	SW 14
Supply Current	OFF	OFF	OFF	ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
Maximum Output Voltage(High)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF
Maximum Output Voltage(Low)	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF
Output Source Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Output Sink Current	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON
Slew Rate	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	OFF
Gain Bandwidth Product	OFF	ON	OFF	OFF	ON	ON	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF
Equivalent Input Noise Voltage	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF

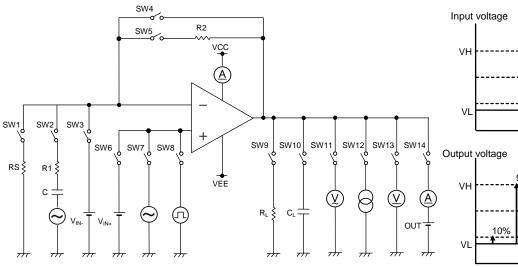


Figure 99. Test Circuit 2 (each Op-Amp)

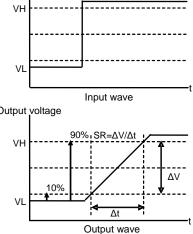
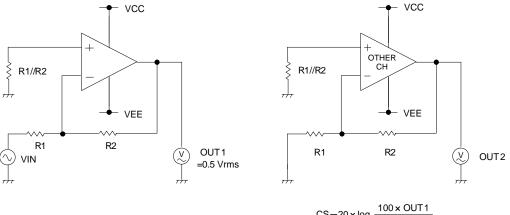
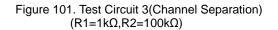


Figure 100. Slew Rate Input Waveform

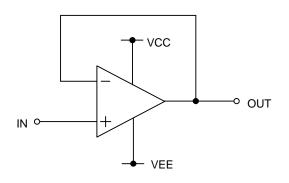


 $CS=20 \times \log \frac{100 \times 001}{OUT2}$ 



# **Examples of circuit**

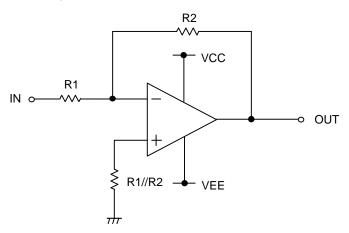
OVoltage follower



Voltage gain is 0 dB.

This circuit controls output voltage (OUT) equal input voltage (IN), and keeps OUT with stable because of high input impedance and low output impedance. OUT is shown next formula. OUT=IN

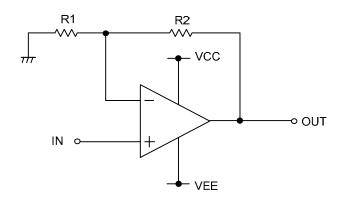
# OInverting amplifier



For inverting amplifier, IN is amplified by voltage gain decided R1 and R2, and phase reversed voltage is output.

OUT is shown next formula. OUT=-(R2/R1) IN Input impedance is R1.

ONon-inverting amplifier



For non-inverting amplifier, IN is amplified by voltage gain decided R1 and R2, and phase is same with IN. OUT is shown next formula.  $OUT = (1+R2/R1) \cdot IN$ 

This circuit realizes high input impedance because Input impedance is operational amplifier's input Impedance.

# **Power Dissipation**

Power dissipation (total loss) indicates the power that the IC can consume at  $T_A=25$ °C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol  $\theta_{JA}$ °C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 102 (a) shows the model of the thermal resistance of a package. The equation below shows how to compute for the Thermal resistance ( $\theta_{JA}$ ), given the ambient temperature ( $T_A$ ), maximum junction temperature ( $T_{Jmax}$ ), and power dissipation ( $P_D$ ).

$$\theta_{JA} = (T_{Jmax} - T_A) / P_D \circ C/W$$

The derating curve in Figure 102 (b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance ( $\theta_{JA}$ ), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same of package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 102. (c) to (f) show a derating curve for an example of BA10358, BA10324A, BA2904S, BA2904W, BA2902S, BA2902.

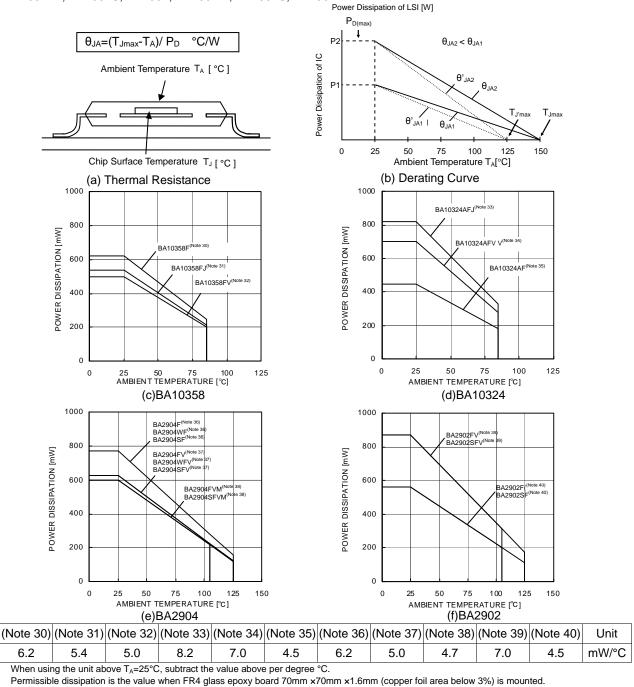


Figure 102. Thermal resistance and derating

# **Operational Notes**

# 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply terminals.

# 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance ground and supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

# 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

# 4. Ground Wiring Pattern

When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the GND traces of external components do not cause variations on the GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

# 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded, the rise in temperature of the chip may result in deterioration of the properties of the chip. The absolute maximum rating of the Pd stated in this specification is when the IC is mounted on a 70mm x 70mm x 1.6mm glass epoxy board. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

# 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

# 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

# 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

# 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

# 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

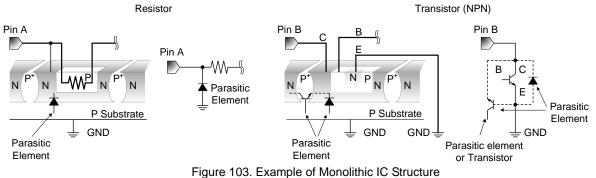
# **Operational Notes – continued**

## 11. Regarding Input Pins of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



#### 12. Unused Circuits

When there are unused circuits it is recommended that they be connected as in Figure 104, setting the non-inverting input terminal to a potential within the in-phase input voltage range ( $V_{ICM}$ ).

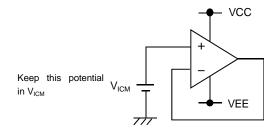


Figure 104. Disable Circuit Example

# 13. Input Terminal Voltage

(BA10358 / BA10324) Applying VEE + 32V, (BA2904 / BA2902) Applying VEE + 36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, irrespective of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.

# 14. Power Supply (signal / dual)

The op-amp operates when the specified voltage supplied is between VCC and VEE. Therefore, the single supply op-amp can be used as a dual supply op-amp as well.

#### 15. Terminal short-circuits

When the output and VCC terminals are shorted, excessive output current may flow, resulting in undue heat generation and, subsequently, destruction.

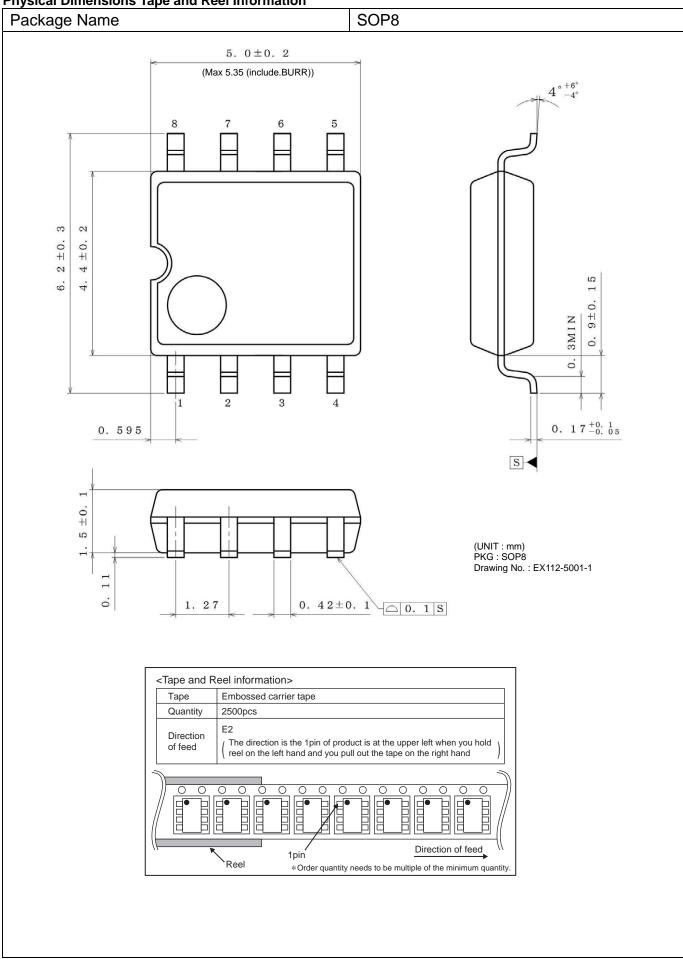
#### 16. IC Handling

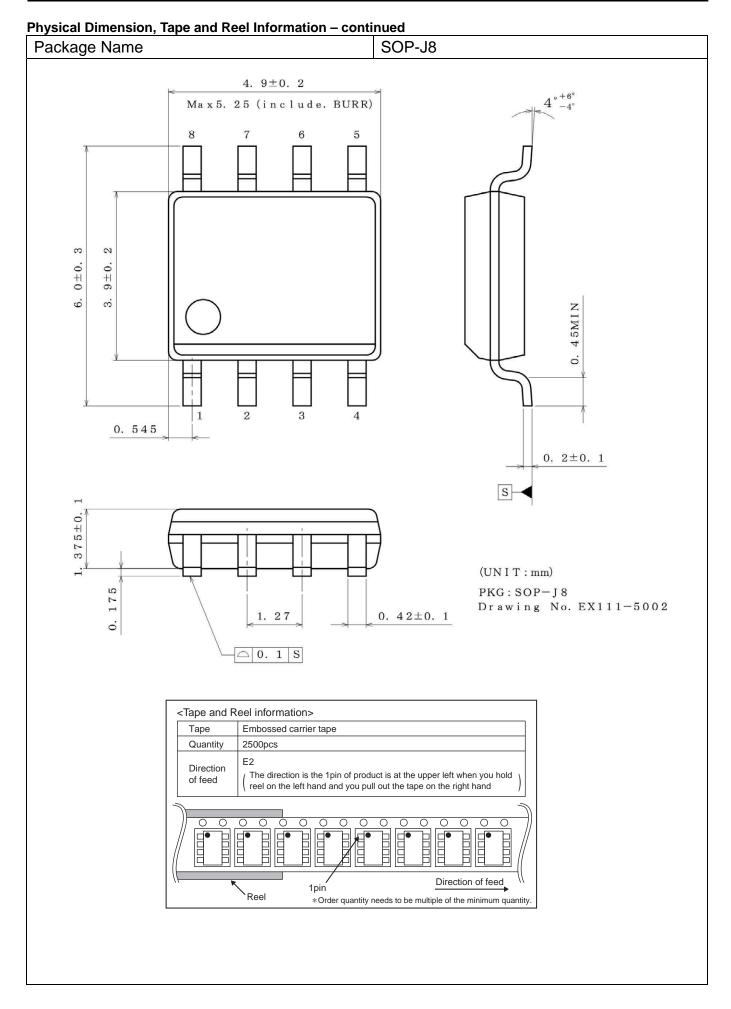
Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations in the electrical characteristics due to piezo resistance effects.

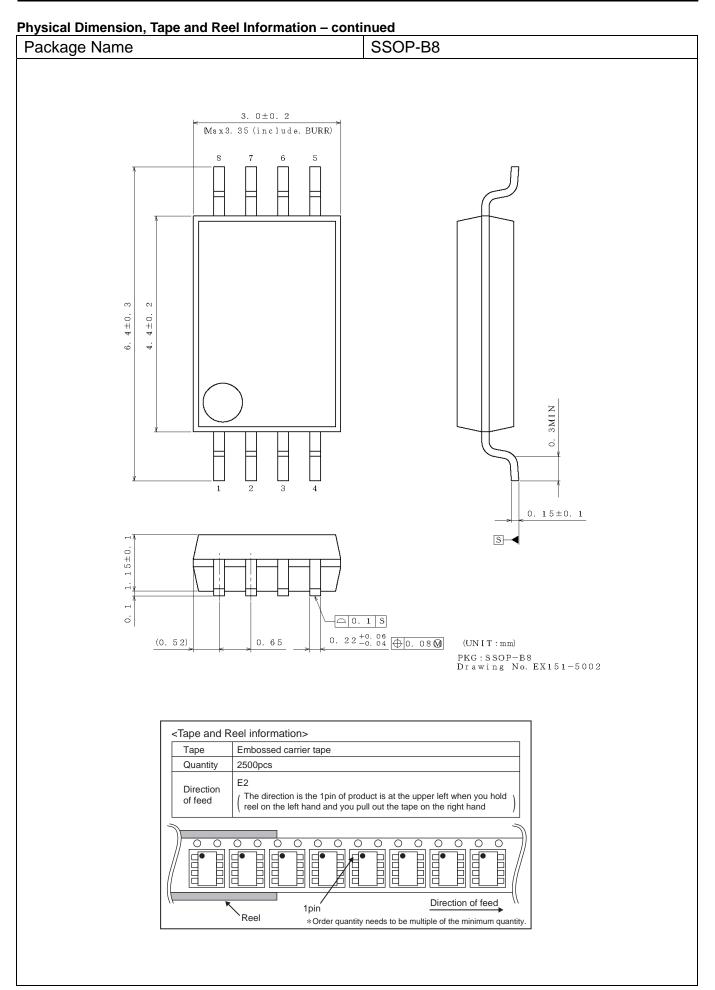
# 17. Output Capacitor

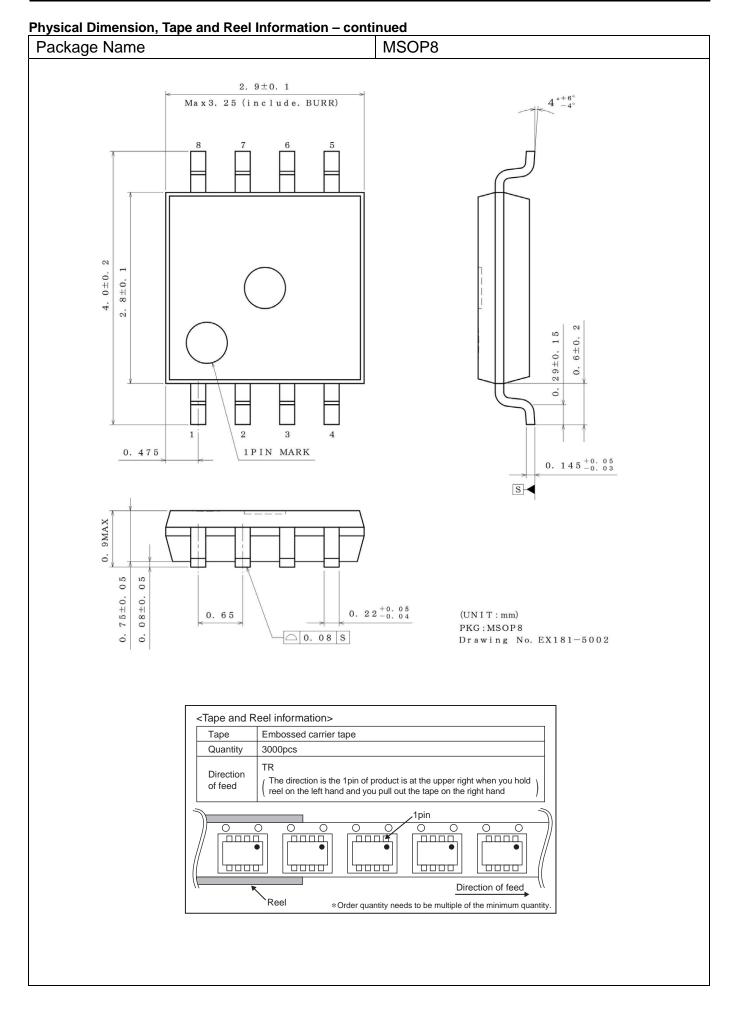
If a large capacitor is connected between the output pin and VEE pin, current from the charged capacitor will flow into the output pin and may destroy the IC when the VCC pin is shorted to ground or pulled down to 0V. Use a capacitor smaller than 0.1uF between output pin and VEE pin.

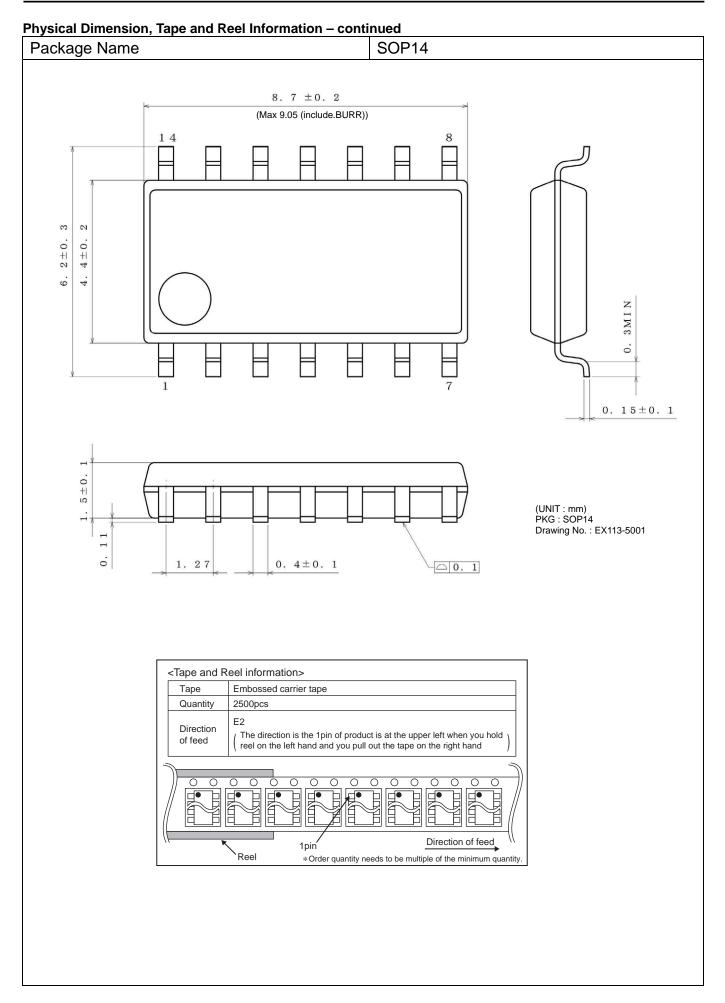
# Physical Dimensions Tape and Reel Information

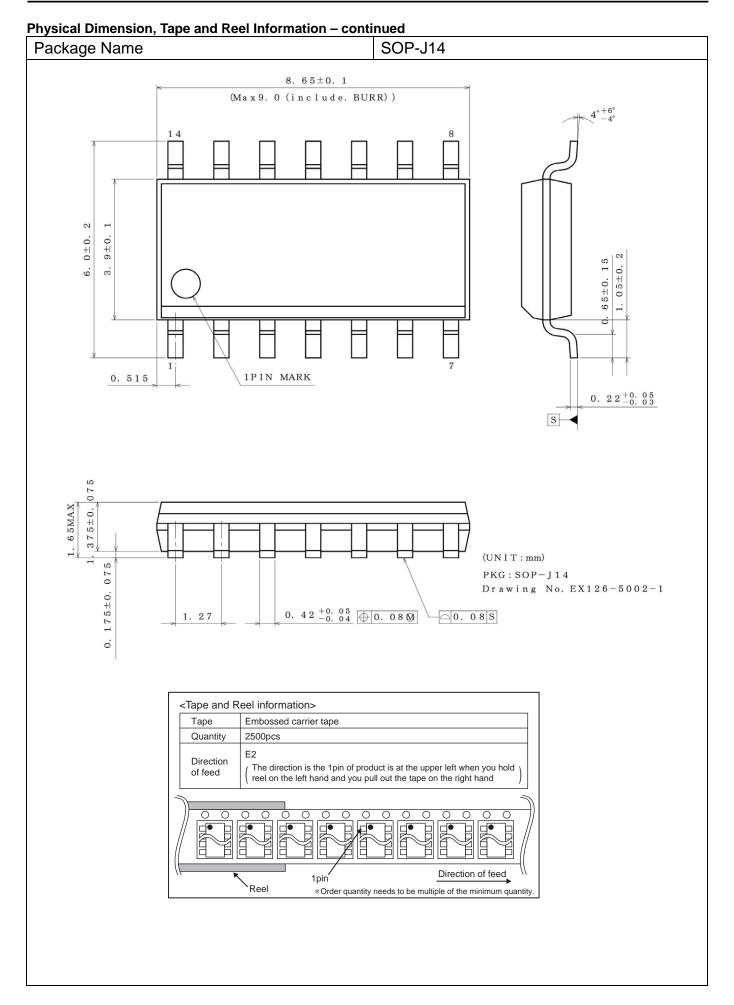




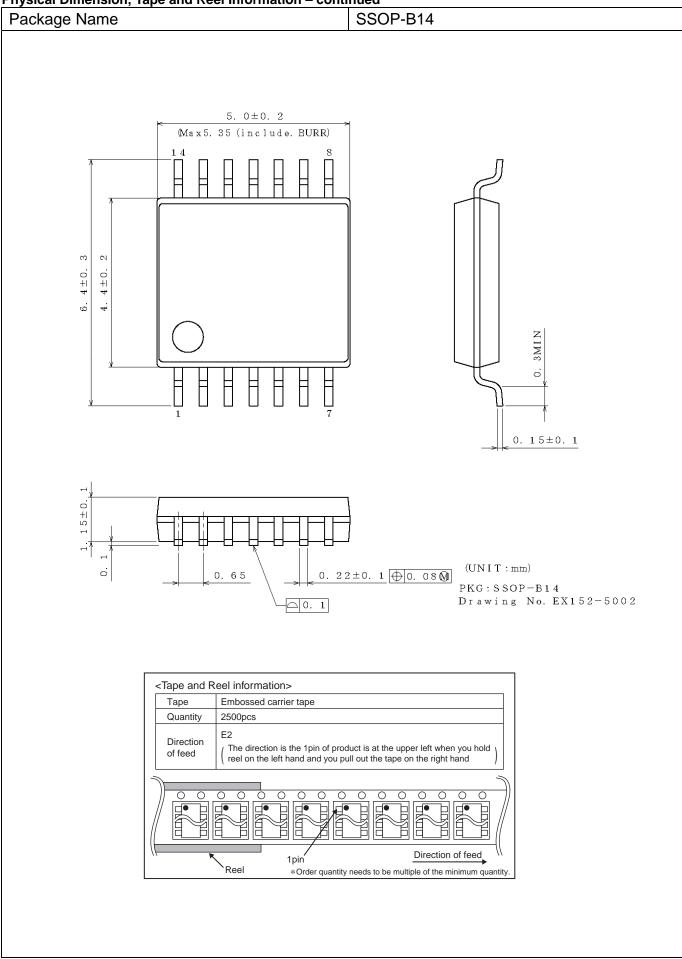




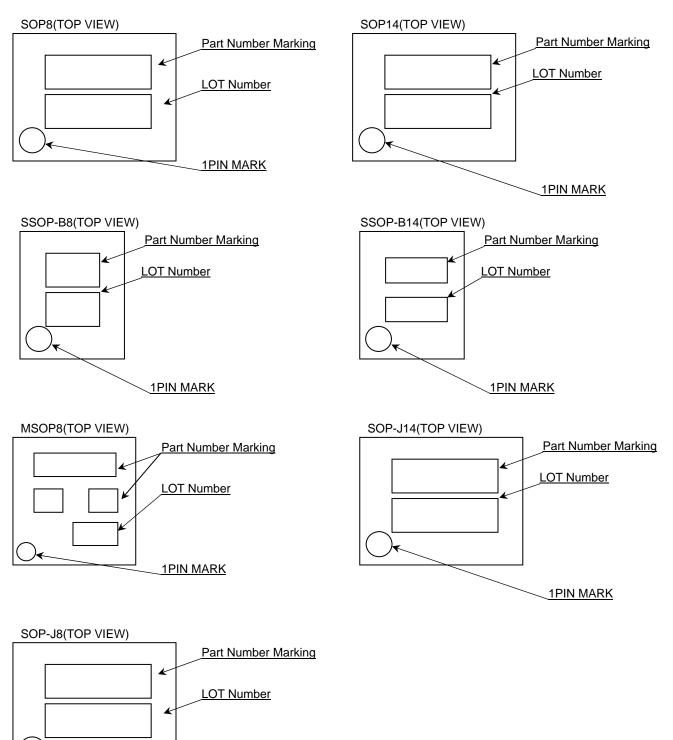








# **Marking Diagrams**

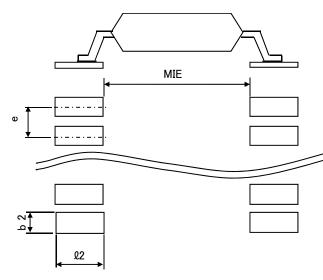


1PIN MARK

Product N	lame	Package Type	Marking
	F	SOP8	10358
BA10358	FJ	SOP-J8	10550
	FV	SSOP-B8	358
	F	SOP14	BA10324AF
BA10324A	FJ	SOP-J14	BA10324A
	FV	SSOP-B14	324A
	F	SOP8	
BA2904	FV	SSOP-B8	
	FVM	MSOP8	2904
DA 200 414/	F	SOP8	
BA2904W	FV	SSOP-B8	
	F	SOP8	2904S
BA2904S	FV	SSOP-B8	04S
	FVM	MSOP8	2904S
B 4 2002	F	SOP14	BA2902F
BA2902	FV	SSOP-B14	2902
BA20028	F	SOP14	20026
BA2902S	FV	SSOP-B14	2902S

# Land pattern data

			all dir	mensions in mm
PKG	Land pitch	Land space	Land length	Land width
FKG	е	MIE	≧ℓ 2	b2
SOP8	1.27	4.60	1.10	0.76
SSOP-B8	0.65	4.60	1.20	0.35
SOP-J8	1.27	3.90	1.35	0.76
MSOP8	0.65	2.62	0.99	0.35
SOP14	1.27	4.60	1.10	0.76
SSOP-B14	0.65	4.60	1.20	0.35
SOP-J14	1.27	3.90	1.35	0.76



SOP8, SSOP-B8, SOP-J8, MSOP8 SOP14, SSOP-B14, SOP-J14

# **Revision History**

Date	Revision	Changes
14.SEP.2012	001	New Release
11.Jan.2013	002	Land pattern data inserted.
23.Jan.2014	003	The Differential Input Voltage and Input Common-mode Voltage Range are updated in absolute maximum ratings for BA10358 and BA10324A. The input current is added in absolute maximum ratings.

# Notice

# Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSⅢ		CLASS II b	
CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

# Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

# **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

## **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

## **Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

#### Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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